

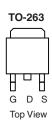
N-Channel 250-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)		
250	0.165 at V _{GS} = 10 V	18		

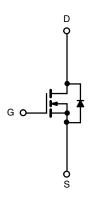
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package





Ordering Information: SUM18N25-165-E3 (Lead (Pb)-free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	250	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C	. I _D	18		
	T _C = 125 °C		10.4		
Pulsed Drain Current		I _{DM}	20	A	
Single Pulse Avalanche Current		I _{AS}	5		
Single Pulse Avalanche Energy ^a	L = 0.1 mH	E _{AS}	1.25	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	В	150 ^b	W	
	T _A = 25 °C ^c	P_{D}	3.75	l vv	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) ^c	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)		R _{thJC}	1.0	- O/VV	

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	250			V
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5		4	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current		V _{DS} = 250 V, V _{GS} = 0 V			1	μΑ
	I _{DSS}	V _{DS} = 250 V, V _{GS} = 0 V, T _J = 125 °C			50	
		$V_{DS} = 250 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 15 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 14 A		0.130	0.165	Ω
	r _{DS(on)}	V _{GS} = 10 V, I _D = 14 A, T _J = 125 °C			0.347	
		V _{GS} = 10 V, I _D = 14 A, T _J = 175 °C			0.462	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 18 A		36		S
Dynamic ^b	•			•		
Input Capacitance	C _{iss}			1950		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		160		
Reverse Transfer Capacitance	C _{rss}			70		
Total Gate Charge ^c	Q_g			30	45	nC
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 125 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 18 \text{ A}$		10		
Gate-Drain Charge ^c	Q_{gd}			10		
Gate Resistance	R _g			1.6		Ω
Turn-On Delay Time ^c	t _{d(on)}			15	25	ns
Rise Time ^c	t _r	V_{DD} = 125 V, R _L = 7.0 Ω I _D \cong 18 A, V _{GEN} = 10 V, R _g = 2.5 Ω		130	195	
Turn-Off Delay Time ^c	t _{d(off)}			30	45	
Fall Time ^c	t _f			100	150	
Source-Drain Diode Ratings and Cha	aracteristics 7	_C = 25 °C ^b				
Continuous Current	Is				18	
Pulsed Current	I _{SM}				20	Α
Forward Voltage ^a	V _{SD}	I _F = 18 A, V _{GS} = 0 V		1.0	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 18 A, di/dt = 100 A/μs		115	175	ns
Peak Reverse Recovery Charge	I _{RM(REC)}			10	15	Α
Reverse Recovery Charge	Q _{rr}			0.58	1.3	μС

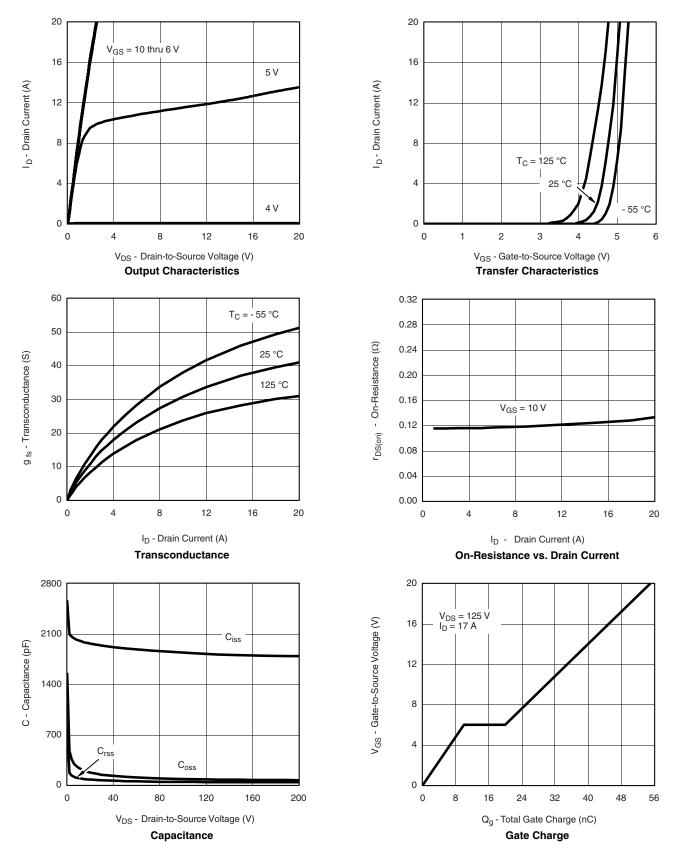
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



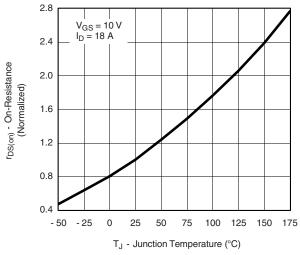
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



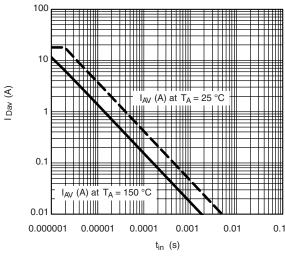
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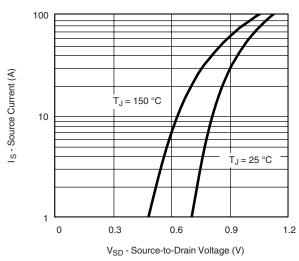
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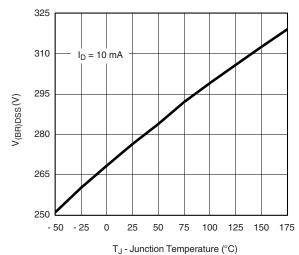
On-Resistance vs. Junction Temperature



Avalanche Current vs. Time



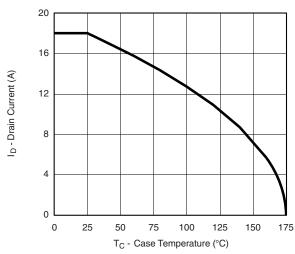
Source-Drain Diode Forward Voltage



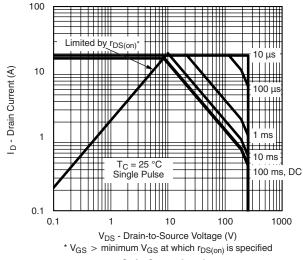
Drain Source Breakdown vs.
Junction Temperature



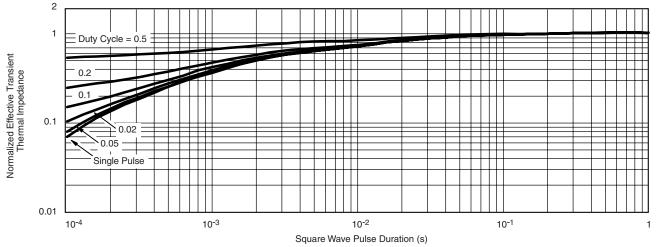
THERMAL RATINGS



Maximum Drain Current vs. Case Temperature







Normalized Thermal Transient Impedance, Junction-to-Case

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